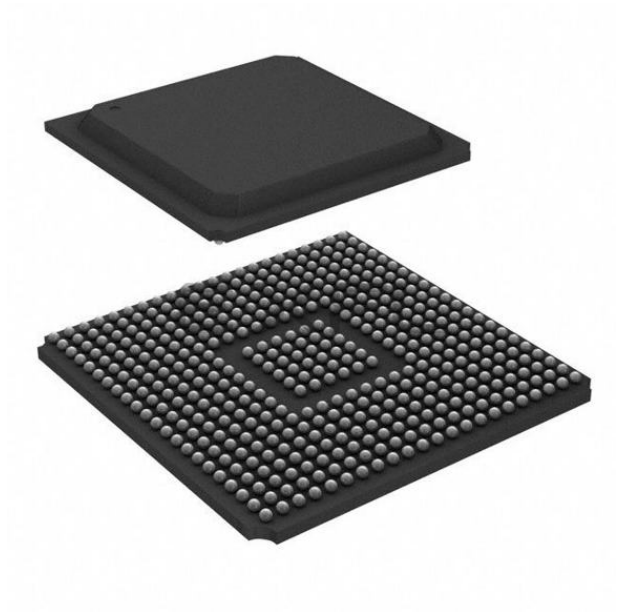
AMD Xilinx - XC2VP4-6FGG456C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	752
Number of Logic Elements/Cells	6768
Total RAM Bits	516096
Number of I/O	248
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	456-BBGA
Supplier Device Package	456-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp4-6fgg456c

- Programmable Receiver Equalization
- Internal AC Coupling
- On-Chip 50Ω Termination
  - Eliminates the need for external termination resistors
- Pre- and Post-Driver Serial and Parallel TX-to-RX Internal Loopback Modes for Testing Operability
- Programmable Comma Detection
  - Allows for any protocol
  - Allows for detection of any 10-bit character
- 8B/10B and 64B/66B Encoding Blocks

RocketIO Transceiver Features (All Except XC2VPX20 and XC2VPX70)

- Full-Duplex Serial Transceiver (SERDES) Capable of Baud Rates from 600 Mb/s to 3.125 Gb/s
- 100 Gb/s Duplex Data Rate (20 Channels)
- Monolithic Clock Synthesis and Clock Recovery (CDR)
- Fibre Channel, 10G Fibre Channel, Gigabit Ethernet, 10 Gb Attachment Unit Interface (XAUI), and Infiniband-Compliant Transceivers
- 8-, 16-, or 32-bit Selectable Internal FPGA Interface
- 8B/10B Encoder and Decoder (optional)
- 50Ω/75Ω on-chip Selectable Transmit and Receive Terminations
- Programmable Comma Detection
- Channel Bonding Support (from 2 to 20 Channels)
- Rate Matching via Insertion/Deletion Characters
- Four Levels of Selectable Pre-Emphasis
- Five Levels of Output Differential Voltage
- Per-Channel Internal Loopback Modes
- 2.5V Transceiver Supply Voltage

PowerPC RISC Processor Block Features (All Except XC2VP2)

- Embedded 300+ MHz Harvard Architecture Block
- Low Power Consumption: 0.9 mW/MHz
- Five-Stage Data Path Pipeline
- Hardware Multiply/Divide Unit
- Thirty-Two 32-bit General Purpose Registers
- 16 KB Two-Way Set-Associative Instruction Cache
- 16 KB Two-Way Set-Associative Data Cache
- Memory Management Unit (MMU)
  - 64-entry unified Translation Look-aside Buffers (TLB)
  - Variable page sizes (1 KB to 16 MB)
- Dedicated On-Chip Memory (OCM) Interface
- Supports IBM CoreConnect™ Bus Architecture
- Debug and Trace Support
- Timer Facilities

Virtex-II Pro Platform FPGA Technology (All Devices)

- SelectRAM+ Memory Hierarchy
  - Up to 8 Mb of True Dual-Port RAM in 18 Kb block SelectRAM+ resources
  - Up to 1,378 Kb of distributed SelectRAM+ resources
  - High-performance interfaces to external memory
- Arithmetic Functions
  - Dedicated 18-bit x 18-bit multiplier blocks
  - Fast look-ahead carry logic chains
- Flexible Logic Resources
  - Up to 88,192 internal registers/latches with Clock Enable
  - Up to 88,192 look-up tables (LUTs) or cascadable variable (1 to 16 bits) shift registers
  - Wide multiplexers and wide-input function support
  - Horizontal cascade chain and Sum-of-Products support
  - Internal 3-state busing
- High-Performance Clock Management Circuitry
  - Up to twelve Digital Clock Manager (DCM) modules
    - Precise clock de-skew
    - Flexible frequency synthesis
    - High-resolution phase shifting
  - 16 global clock multiplexer buffers in all parts
- Active Interconnect Technology
  - Fourth-generation segmented routing structure
  - Fast, predictable routing delay, independent of fanout
  - Deep sub-micron noise immunity benefits
- SelectIO™-Ultra Technology
  - Up to 1,164 user I/Os
  - Twenty-two single-ended standards and ten differential standards
  - Programmable LVCMOS sink/source current (2 mA to 24 mA) per I/O
  - XCITE Digitally Controlled Impedance (DCI) I/O
  - PCI/PCI-X support (1)
  - Differential signaling
    - 840 Mb/s Low-Voltage Differential Signaling I/O (LVDS) with current mode drivers
    - On-chip differential termination
    - Bus LVDS I/O

1. Refer to XAPP653 for more information.

Each RocketIO or RocketIO X core implements the following technology:

- Serializer and deserializer (SERDES)
- Monolithic clock synthesis and clock recovery (CDR)
- 10 Gigabit Attachment Unit Interface (XAUI) Fibre Channel (3.1875 Gb/s XAUI), Infiniband, PCI Express, Aurora, SXI-5 (SFI-5,/SPI-5), and OC-48 compatibility(1)
- 8/16/32-bit (RocketIO) or 8/16/32/64-bit (RocketIO X) selectable FPGA interface
- 8B/10B (RocketIO) or 8B/10B and 64B/66B (RocketIO X) encoder and decoder with bypassing option on each channel
- Channel bonding support (two to twenty channels)
  - Elastic buffers for inter-chip deskewing and channel-to-channel alignment
- Receiver clock recovery tolerance of up to 75 non-transitioning bits
- 50Ω (RocketIO X) or 50Ω /75Ω selectable (RocketIO) on-chip transmit and receive terminations
- Programmable comma detection and word alignment
- Rate matching via insertion/deletion characters
- Automatic lock-to-reference function
- Programmable pre-emphasis support
- Per-channel serial and parallel transmitter-to-receiver internal loopback modes
- Optional transmit and receive data inversion
- Cyclic Redundancy Check support (RocketIO only)

PowerPC 405 Processor Block

The PPC405 RISC CPU can execute instructions at a sustained rate of one instruction per cycle. On-chip instruction and data cache reduce design complexity and improve system throughput.

The PPC405 features include:

- PowerPC RISC CPU
  - Implements the PowerPC User Instruction Set Architecture (UISA) and extensions for embedded applications
  - Thirty-two 32-bit general purpose registers (GPRs)
  - Static branch prediction
  - Five-stage pipeline with single-cycle execution of most instructions, including loads/stores
  - Unaligned and aligned load/store support to cache, main memory, and on-chip memory
  - Hardware multiply/divide for faster integer arithmetic (4-cycle multiply, 35-cycle divide)
  - Enhanced string and multiple-word handling
  - Big/little endian operation support
- Storage Control
  - Separate instruction and data cache units, both two-way set-associative and non-blocking
  - Eight words (32 bytes) per cache line
  - 16 KB array Instruction Cache Unit (ICU), 16 KB array Data Cache Unit (DCU)
  - Operand forwarding during instruction cache line fill
  - Copy-back or write-through DCU strategy
  - Doubleword instruction fetch from cache improves branch latency
- Virtual mode memory management unit (MMU)
  - Translation of the 4 GB logical address space into physical addresses
  - Software control of page replacement strategy
  - Supports multiple simultaneous page sizes ranging from 1 KB to 16 MB
- OCM controllers provide dedicated interfaces between Block SelectRAM+ memory and processor block instruction and data paths for high-speed access
- PowerPC timer facilities
  - 64-bit time base
  - Programmable interval timer (PIT)
  - Fixed interval timer (FIT)
  - Watchdog timer (WDT)
- Debug Support
  - Internal debug mode
  - External debug mode
  - Debug Wait mode
  - Real Time Trace debug mode
  - Enhanced debug support with logical operators
  - Instruction trace and trace-back support
  - Forward or backward trace
- Two hardware interrupt levels support
- Advanced power management support

Input/Output Blocks (IOBs)

IOBs are programmable and can be categorized as follows:

- Input block with an optional single data rate (SDR) or double data rate (DDR) register
- Output block with an optional SDR or DDR register and an optional 3-state buffer to be driven directly or through an SDR or DDR register
- Bidirectional block (any combination of input and output configurations)

These registers are either edge-triggered D-type flip-flops or level-sensitive latches.

IOBs support the following single-ended I/O standards:

- LVTTL, LVCMOS (3.3V,(2) 2.5V, 1.8V, and 1.5V)
- PCI-X compatible (133 MHz and 66 MHz) at 3.3V(3)
- PCI compliant (66 MHz and 33 MHz) at 3.3V(3)
- GTL and GTLP

1. Refer to Table 4, Module 2 for detailed information about RocketIO and RocketIO X transceiver compatible protocols.
2. Refer to **XAPP659** for more information.
3. Refer to **XAPP653** for more information.

Other RocketIO X Features and Notes

Loopback

In order to facilitate testing without having the need to either apply patterns or measure data at GHz rates, four programmable loop-back features are available.

The first option, serial loopback, is available in two modes: *pre-driver* and *post-driver*.

- The pre-driver mode loops back to the receiver without going through the output driver. In this mode, TXP and TXN are not driven and therefore need not be terminated.
- The post-driver mode is the same as the RocketIO loopback. In this mode, TXP and TXN are driven and must be properly terminated.

The third option, parallel loopback, checks the digital circuitry. When parallel loopback is enabled, the serial loopback path is disabled. However, the transmitter outputs remain active, and data can be transmitted. If TXINHIBIT is asserted, TXP is forced to 0 until TXINHIBIT is de-asserted.

The fourth option, repeater loopback, allows received data to be transmitted without going through the FPGA fabric.

Reset

The receiver and transmitter have their own synchronous reset inputs. The transmitter reset, TXRESET, recenters the transmission FIFO and resets all transmitter registers and the encoder. The receiver reset, RXRESET, recenters the receiver elastic buffer and resets all receiver registers and the decoder. When the signals TXRESET or RXRESET are asserted High, the PCS is in reset. After TXRESET or RXRESET are deasserted, the PCS takes five clocks to come out of reset for each clock domain.

The PMA configuration vector is not affected during this reset, so the PMA speed, filter settings, and so on, all remain the same. Also, the PMA internal pipeline is not affected and continues to operate in normal fashion.

Power

The transceiver voltage regulator circuits must not be shared with any other supplies (including FPGA supplies V_{CCINT}, V_{CCO}, V_{CCAUX}, and V_{REF}). Voltage regulators can be shared among transceiver power supplies of the same voltage, but each supply pin must still have its own separate passive filtering network.

All RocketIO transceivers in the FPGA, whether instantiated in the design or not, must be connected to power and ground. Unused transceivers can be powered by any 1.5V or 2.5V source, and passive filtering is not required.

The Power Down feature is controlled by the transceiver's POWERDOWN input pin. Any given transceiver that is not instantiated in the design is automatically set to the POWERDOWN state by the Xilinx ISE development software. The Power Down pin on the FPGA package has no effect on the MGT.

Receiver Buffer

The receiver includes buffers (FIFOs) in the datapath. This section gives the reasons for including the buffers and outlines their operation.

The receiver buffer is required for two reasons:

- *Clock correction* to accommodate the slight difference in frequency between the recovered clock RXRECCLK and the internal FPGA user clock RXUSRCLK
- *Channel bonding* to allow realignment of the input stream to ensure proper alignment of data being read through multiple transceivers

The receiver uses an *elastic buffer,* where "elastic" refers to the ability to modify the read pointer for clock correction and channel bonding.

Comma Detection

Word alignment is dependent on the state of comma detect bits. If comma detect is enabled, the transceiver recognizes up to two 10-bit preprogrammed characters. Upon detection of the character or characters, the comma detect output is driven high and the data is synchronously aligned. If a comma is detected and the data is aligned, no further alignment alteration takes place. If a comma is received and realignment is necessary, the data is realigned and an indication is given at the receiver interface. The realignment indicator is a distinct output.

The transceiver continuously monitors the data for the presence of the 10-bit character(s). Upon each occurrence of a 10-bit character, the data is checked for word alignment. If comma detect is disabled, the data is not aligned to any particular pattern. The programmable option allows a user to align data on comma+, comma–, both, or a unique user-defined and programmed sequence.

Clock Correction

RXRECCLK (the recovered clock) reflects the data rate of the incoming data. RXUSRCLK defines the rate at which the FPGA fabric consumes the data. Ideally, these rates are identical. However, since the clocks typically have different sources, one of the clocks will be faster than the other. The receiver buffer accommodates this difference between the clock rates. See Figure 12.

Nominally, the buffer is always half full. This is shown in the top buffer, Figure 12, where the shaded area represents buffered data not yet read. Received data is inserted via the write pointer under control of RXRECCLK. The FPGA fabric reads data via the read pointer under control of RXUSRCLK. The half full/half empty condition of the buffer gives a cushion for the differing clock rates. This operation continues indefinitely, regardless of whether or not "meaningful" data is being received. When there is no meaningful data to be received, the incoming data will consist of IDLE characters or other padding.

If RXUSRCLK is faster than RXRECCLK, the buffer becomes more empty over time. The clock correction logic corrects for this by decrementing the read pointer to reread a repeatable byte sequence. This is shown in the middle buffer, Figure 12, where the solid read pointer decrements to the value represented by the dashed pointer.

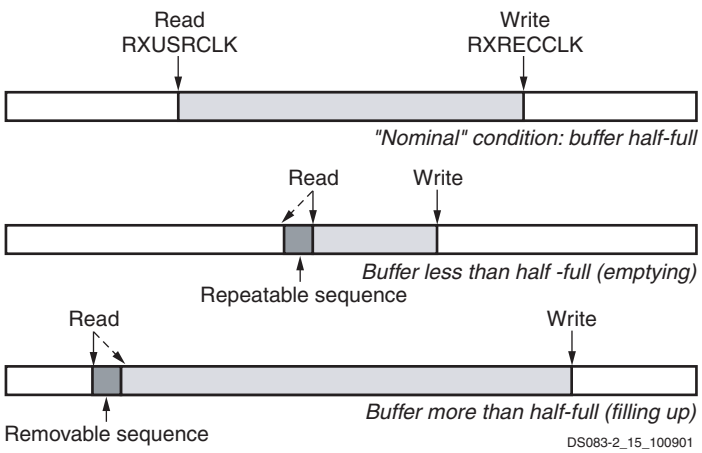


Figure 12: **Clock Correction in Receiver**

By decrementing the read pointer instead of incrementing it in the usual fashion, the buffer is partially refilled. The transceiver design will repeat a single repeatable byte sequence when necessary to refill a buffer. If the byte sequence length is greater than one, and if attribute CLK_COR_REPEAT_WAIT is 0, then the transceiver may repeat the same sequence multiple times until the buffer is refilled to the desired extent.

Similarly, if RXUSRCLK is slower than RXRECCLK, the buffer will fill up over time. The clock correction logic corrects for this by incrementing the read pointer to skip over a removable byte sequence that need not appear in the final FPGA fabric byte stream. This is shown in the bottom buffer, Figure 12, where the solid read pointer increments to the value represented by the dashed pointer. This accelerates the emptying of the buffer, preventing its overflow. The transceiver design will skip a single byte sequence when necessary to partially empty a buffer. If attribute CLK_COR_REPEAT_WAIT is 0, the transceiver may also skip two consecutive removable byte sequences in one step to further empty the buffer when necessary.

These operations require the clock correction logic to recognize a byte sequence that can be freely repeated or omitted in the incoming data stream. This sequence is generally an IDLE sequence, or other sequence comprised of special values that occur in the gaps separating packets of meaningful data. These gaps are required to occur sufficiently often to facilitate the timely execution of clock correction.

Channel Bonding

Some gigabit I/O standards such as Infiniband specify the use of multiple transceivers in parallel for even higher data rates. Words of data are split into bytes, with each byte sent over a separate channel (transceiver). See Figure 13.

Table 15: **SelectIO-Ultra Differential Buffers With On-Chip Termination**

I/O Standard Description	IOSTANDARD Attribute	
	External Termination	On-Chip Termination
LVDS 2.5V	LVDS_25	LVDS_25_DCI
LVDS Extended 2.5V	LVDSEXT_25	LVDSEXT_25_DCI

Figure 28 provides examples illustrating the use of the HSTL_I_DCI, HSTL_II_DCI, HSTL_III_DCI, and HSTL_IV_DCI I/O standards. For a complete list, see the ***Virtex-II Pro Platform FPGA User Guide***.

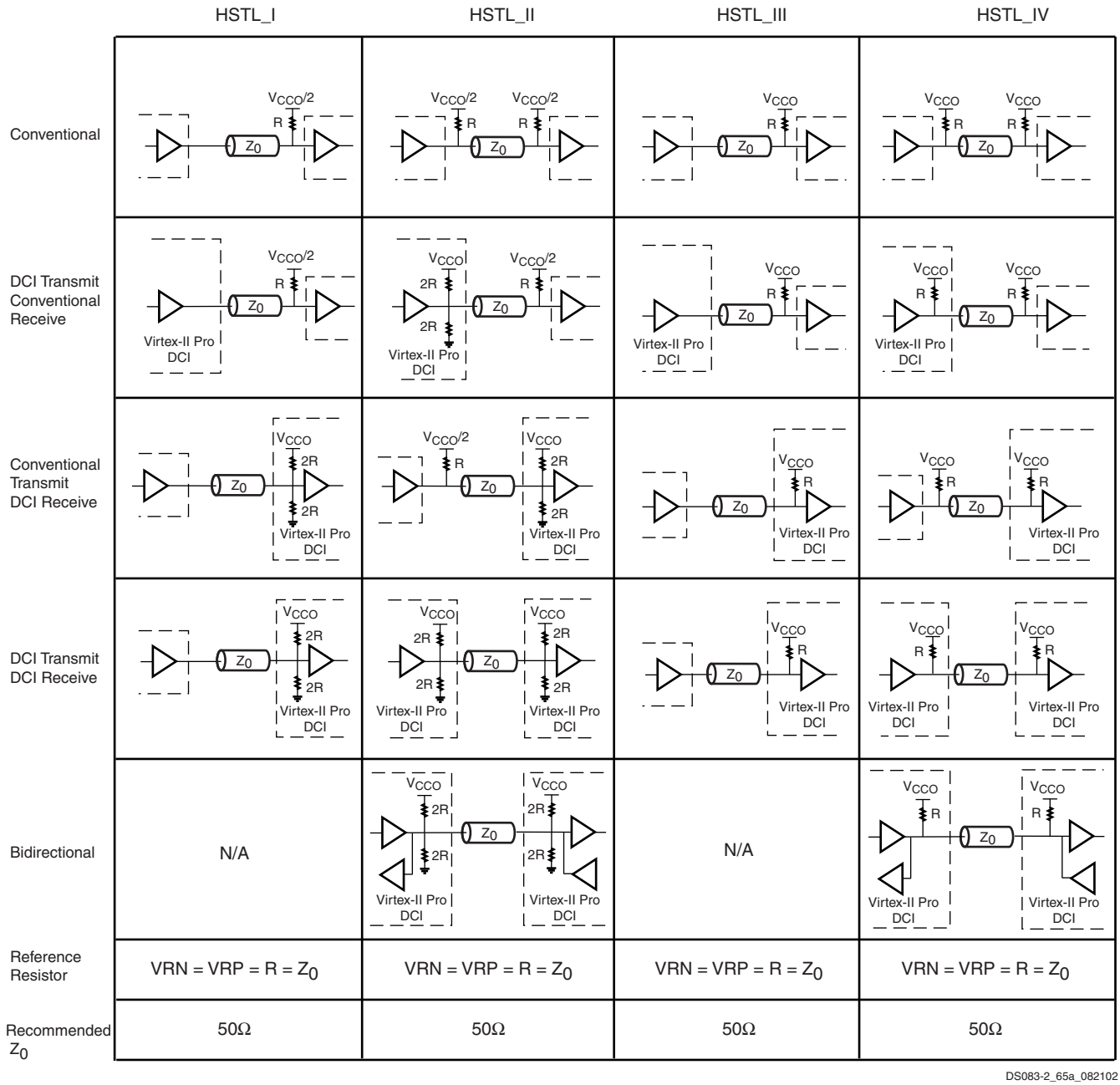


Figure 28: **HSTL DCI Usage Examples**

LVDS DC Specifications (LVDS_25)

Table 8: **LVDS DC Specifications**

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.38	2.5	2.63	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals			1.602	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.898			V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	247	350	454	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.250	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25V	100	350	600	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.3	1.2	2.2	V

Extended LVDS DC Specifications (LVDSEXT_25)

Table 9: **Extended LVDS DC Specifications**

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.38	2.5	2.63	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals			1.785	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.715			V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	440		820	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.250	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25V	100		1000	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.3	1.2	2.2	V

LVPECL DC Specifications (LVPECL_25)

These values are valid when driving a 100 Ω differential load only, i.e., a 100 Ω resistor between the two receiver pins. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. Table 10 summarizes the DC output specifications of LVPECL. For more information on using LVPECL, see the *Virtex-II Pro Platform FPGA User Guide*.

Table 10: **LVPECL DC Specifications**

DC Parameter	V_{CCO} = 2.375V		V_{CCO} = 2.5V		V_{CCO} = 2.625V		Units
	Min	Max	Min	Max	Min	Max	
V_{OH}	1.35	1.495	1.475	1.62	1.6	1.745	V
V_{OL}	0.565	0.755	0.69	0.88	0.815	1.005	V
V_{IH}	0.8	2.0	0.8	2.0	0.8	2.0	V
V_{IL}	0.5	1.7	0.5	1.7	0.5	1.7	V
Differential Input Voltage	0.100	1.5	0.100	1.5	0.100	1.5	V

Table 14 shows internal (register-to-register) performance. Values are reported in MHz.

Table 14: **Register-to-Register Performance**

Description	Device Used & Speed Grade	Register-to-Register Performance	Units
Basic Functions:			
16-bit Address Decoder	XC2VP20FF1152-6	547	MHz
32-bit Address Decoder	XC2VP20FF1152-6	392	MHz
64-bit Address Decoder	XC2VP20FF1152-6	310	MHz
4:1 MUX	XC2VP20FF1152-6	710	MHz
8:1 MUX	XC2VP20FF1152-6	609	MHz
16:1 MUX	XC2VP20FF1152-6	472	MHz
32:1 MUX	XC2VP20FF1152-6	400	MHz
Register to LUT to Register	XC2VP20FF1152-6	1046	MHz
8-bit Adder	XC2VP20FF1152-6	337	MHz
16-bit Adder	XC2VP20FF1152-6	334	MHz
32-bit Adder	XC2VP20FF1152-6	252	MHz
64-bit Adder	XC2VP20FF1152-6	202	MHz
128-bit Adder	XC2VP20FF1152-6	131	MHz
24-bit Counter	XC2VP20FF1152-6	309	MHz
64-bit Counter	XC2VP20FF1152-6	207	MHz
64-bit Accumulator	XC2VP20FF1152-6	150	MHz
Multiplier 18x18 (with Block RAM inputs)	XC2VP20FF1152-6	135	MHz
Multiplier 18x18 (with Register inputs)	XC2VP20FF1152-6	147	MHz
Memory:			
Block RAM			
Single-Port 4096 x 4 bits	XC2VP20FF1152-6	355	MHz
Distributed RAM			
Single-Port 16 x 8-bit	XC2VP20FF1152-6	555	MHz
Single-Port 32 x 8-bit	XC2VP20FF1152-6	557	MHz
Single-Port 64 x 8-bit	XC2VP20FF1152-6	408	MHz
Single-Port 128 x 8-bit	XC2VP20FF1152-6	336	MHz
Dual-Port 16 x 8-bit	XC2VP20FF1152-6	549	MHz
Dual-Port 32 x 8-bit	XC2VP20FF1152-6	460	MHz
Dual-Port 64 x 8-bit	XC2VP20FF1152-6	407	MHz

Table 65: **Package Skew**

Description	Symbol	Device/Package	Value	Units
Package Skew(1)	$T_{PKGSKEW}$	XC2VP2FF672	104	ps
		XC2VP4FF672	102	ps
		XC2VP7FF672	92	ps
		XC2VP7FF896	101	ps
		XC2VP20FF896	93	ps
		XC2VPX20FF896	93	ps
		XC2VP20FF1152	106	ps
		XC2VP30FF896	86	ps
		XC2VP30FF1152	112	ps
		XC2VP40FF1152	92	ps
		XC2VP40FF1148	100	ps
		XC2VP50FF1152	88	ps
		XC2VP50FF1148	101	ps
		XC2VP50FF1517	97	ps
		XC2VP70FF1517	95	ps
		XC2VP70FF1704	101	ps
		XC2VPX70FF1704	101	ps
		XC2VP100FF1704	86	ps
		XC2VP100FF1696	100	ps

Notes:
1. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball (7.1ps per mm).
2. Package trace length information is available for these device/package combinations. This information can be used to deskew the package.

Table 66: **Sample Window**

Description	Symbol	Device	Speed Grade			Units
			–7	–6	–5	
Sampling Error at Receiver Pins(1)	T_{SAMP}	All	0.50	0.50	0.50	ns

Notes:
1. This parameter indicates the total sampling error of Virtex-II Pro DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation.
2. These measurements include:
   - CLK0 and CLK180 DCM jitter
   - Worst-case duty-cycle distortion, T_{DCD_CLK180}
   - DCM accuracy (phase offset)
   - DCM phase shift resolution

   These measurements do not include package or clock tree skew.

Virtex-II Pro Receiver Data-Valid Window (R_X)

R_X is the required minimum aggregate valid data period for a source-synchronous data bus at the pins of the device and is calculated as follows:

$$R_X = [TSAMP^{(1)} + TCKSKEW^{(2)} + TPKGSKEW^{(3)}]$$

Notes:

1. This parameter indicates the total sampling error of Virtex-II Pro DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation. These measurements include:
   - CLK0 and CLK180 DCM jitter in a quiet system
   - Worst-case duty-cycle distortion
   - DCM accuracy (phase offset)
   - DCM phase shift resolution.

   These measurements do not include package or clock tree skew.
2. This value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to your application.
3. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball.

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
06/17/02	2.0	• Added new Virtex-II Pro family members. • Added timing parameters from speedsfile **v1.62**. • Added Table 46, Pipelined Multiplier Switching Characteristics. • Added 3.3V-vs-2.5V table entries for some parameters.
09/03/02	2.1	• Added Source-Synchronous Switching Characteristics section. • Added absolute max ratings for 3.3V-vs-2.5V parameters in Table 1. • Added recommended operating conditions for V_{IN} and RocketIO footnote to Table 2. • Updated SSTL2 values in Table 6. Added SSTL18 values: Table 6, Table 39, Table 32. [Table 32 removed in v2.8.] • Added Table 10, which contains LVPECL DC specifications.
09/27/02	2.2	Added section General Power Supply Requirements.
11/20/02	2.3	Updated parametric information in: • Table 1: Increase Absolute Max Rating for V_{CCO}, V_{REF}, V_{IN}, and V_{TS} from 3.6V to 3.75V. Delete cautionary footnotes related to voltage overshoot/undershoot. • Table 2: Delete V_{CCO} specifications for 2.5V and below operation. Delete footnote referencing special information for 3.3V operation. Add footnote for PCI/PCI-X. • Table 3: Add I_{BATT}. Delete I_L specifications for 2.5V and below operation. • Table 4: Add Typical Quiescent Supply Currents for XC2VP4 and XC2VP7 only • Table 6: Correct I_{OL} and I_{OH} for SSTL2 I. Add rows for LVTTL, LVCMOS33, and PCI-X. Correct max V_{IH} from V_{CCO} to 3.6V. • Table 7: Correct Min/Max V_{OD}, V_{OCM}, and V_{ICM} • Table 10: Reformat LVPECL DC Specifications to match Virtex-II data sheet format • Table 12: Correct parameter name from Differential Output Voltage to Single-Ended Output Voltage Swing. • Table 16: Add CPMC405CLOCK max frequencies • Table 27: Add footnote regarding serial data rate limitation in -5 part. • Table 39: Add rows for LVTTL, LVCMOS33, and PCI-X. • Table 32: Add LVTTL, LVCMOS33, and PCI-X. Correct all capacitive load values (except PCI/PCI-X) to 0 pF. [Table 32 removed in v2.8.] • Table 51: Correct CCLK max frequencies
11/25/02	2.4	Table 1: Correct lower limit of voltage range of V_{IN} and V_{TS} from –0.3V to –0.5V for 3.3V.

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	VCCO_4		AA11			
4	VCCO_4		AA10			
5	VCCO_5		AB21			
5	VCCO_5		AB20			
5	VCCO_5		AB19			
5	VCCO_5		AB18			
5	VCCO_5		AA21			
5	VCCO_5		AA20			
5	VCCO_5		AA19			
5	VCCO_5		AA18			
5	VCCO_5		AA17			
5	VCCO_5		AA16			
6	VCCO_6		AB22			
6	VCCO_6		AA22			
6	VCCO_6		Y22			
6	VCCO_6		Y21			
6	VCCO_6		W22			
6	VCCO_6		W21			
6	VCCO_6		V22			
6	VCCO_6		V21			
6	VCCO_6		U21			
6	VCCO_6		T21			
7	VCCO_7		R21			
7	VCCO_7		P21			
7	VCCO_7		N22			
7	VCCO_7		N21			
7	VCCO_7		M22			
7	VCCO_7		M21			
7	VCCO_7		L22			
7	VCCO_7		L21			
7	VCCO_7		K22			
7	VCCO_7		J22			
N/A	CCLK		AC7			
N/A	PROG_B		G24			
N/A	DONE		AC8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		C14			
N/A	GND		C3			
N/A	GND		B29			
N/A	GND		B2			
N/A	GND		A22			
N/A	GND		A9			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
4	IO_L73P_4	AG17				
4	IO_L74N_4/GCLK3S	AH17				
4	IO_L74P_4/GCLK2P	AJ17				
4	IO_L75N_4/GCLK1S	AK17				
4	IO_L75P_4/GCLK0P	AL17				
5	IO_L75N_5/GCLK7S	AL18				
5	IO_L75P_5/GCLK6P	AK18				
5	IO_L74N_5/GCLK5S	AJ18				
5	IO_L74P_5/GCLK4P	AH18				
5	IO_L73N_5	AG18				
5	IO_L73P_5	AF18				
5	IO_L69N_5/VREF_5	AL19				
5	IO_L69P_5	AK19				
5	IO_L68N_5	AJ19				
5	IO_L68P_5	AH19				
5	IO_L67N_5	AE18				
5	IO_L67P_5	AD18				
5	IO_L57N_5/VREF_5	AL20				
5	IO_L57P_5	AL21				
5	IO_L56N_5	AJ20				
5	IO_L56P_5	AH20				
5	IO_L55N_5	AG19				
5	IO_L55P_5	AF19				
5	IO_L54N_5	AM22				
5	IO_L54P_5	AM21				
5	IO_L53_5/No_Pair	AK21				
5	IO_L50_5/No_Pair	AJ21				
5	IO_L49N_5	AE19				
5	IO_L49P_5	AD19				
5	IO_L48N_5	AL23				
5	IO_L48P_5	AL22				
5	IO_L47N_5	AH21				
5	IO_L47P_5	AG21				
5	IO_L46N_5	AF20				
5	IO_L46P_5	AE20				
5	IO_L45N_5/VREF_5	AM24				
5	IO_L45P_5	AL24				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

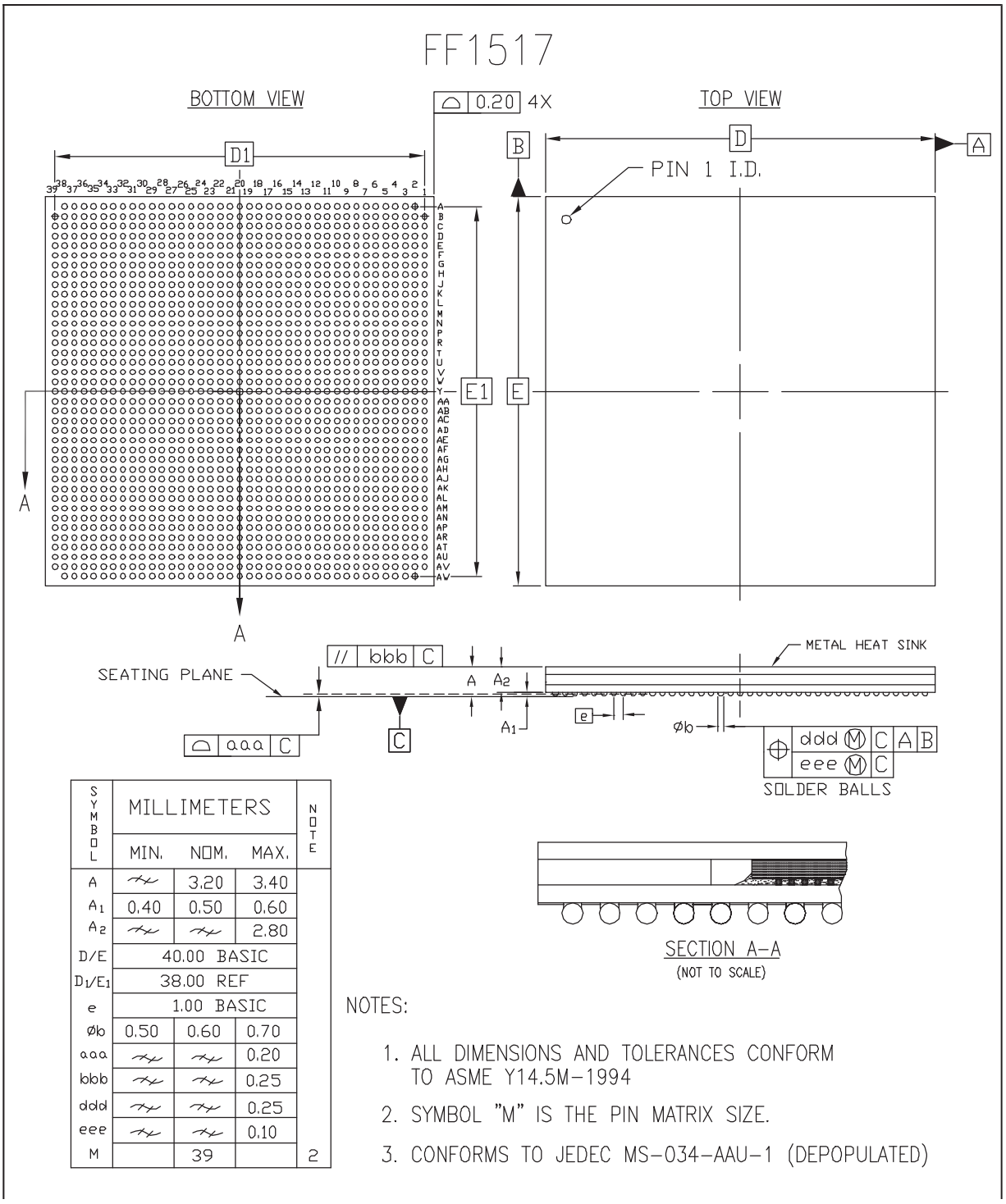
Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
N/A	GND	AG8				
N/A	GND	AG12				
N/A	GND	AG15				
N/A	GND	AG20				
N/A	GND	AG23				
N/A	GND	AG27				
N/A	GND	J34				
N/A	GND	AH7				
N/A	GND	AH28				
N/A	GND	AJ6				
N/A	GND	AJ29				
N/A	GND	AK5				
N/A	GND	AK12				
N/A	GND	AK23				
N/A	GND	AK30				
N/A	GND	AL4				
N/A	GND	AL31				
N/A	GND	AM1				
N/A	GND	AM2				
N/A	GND	AM10				
N/A	GND	AM16				
N/A	GND	AM19				
N/A	GND	AM25				
N/A	GND	AM33				
N/A	GND	AM34				
N/A	GND	AN1				
N/A	GND	AN34				

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L02P_2	D9		
2	IO_L03N_2	B7		
2	IO_L03P_2	A7		
2	IO_L04N_2/VREF_2	B6		
2	IO_L04P_2	A6		
2	IO_L05N_2	E8		
2	IO_L05P_2	D8		
2	IO_L06N_2	B4		
2	IO_L06P_2	A4		
2	IO_L07N_2	B3		
2	IO_L07P_2	A3		
2	IO_L08N_2	H7		
2	IO_L08P_2	H8		
2	IO_L09N_2	C6		
2	IO_L09P_2	C7		
2	IO_L10N_2/VREF_2	C5		
2	IO_L10P_2	B5		
2	IO_L11N_2	K8		
2	IO_L11P_2	J8		
2	IO_L12N_2	C1		
2	IO_L12P_2	C2		
2	IO_L13N_2	E7		
2	IO_L13P_2	D7		
2	IO_L14N_2	J6		
2	IO_L14P_2	J7		
2	IO_L15N_2	D5		
2	IO_L15P_2	D6		
2	IO_L16N_2/VREF_2	E4		
2	IO_L16P_2	D4		
2	IO_L17N_2	L9		
2	IO_L17P_2	K9		
2	IO_L18N_2	E3		
2	IO_L18P_2	D3		
2	IO_L19N_2	D1		
2	IO_L19P_2	D2		
2	IO_L20N_2	K7		
2	IO_L20P_2	L7		
2	IO_L21N_2	F6		

FF1517 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS MIN.	NOM.	MAX.	NOTE
A		3.20	3.40	
A_1	0.40	0.50	0.60	
A_2			2.80	
D/E	40.00 BASIC			
D_1/E_1	38.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa			0.20	
bbb			0.25	
ddd			0.25	
eee			0.10	
M		39		2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAU-1 (DEPOPULATED)

Figure 8: **FF1517 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
2	IO_L86P_2		Y12		
2	IO_L87N_2		AA9		
2	IO_L87P_2		AA10		
2	IO_L88N_2/VREF_2		AA6		
2	IO_L88P_2		AA7		
2	IO_L89N_2		AA12		
2	IO_L89P_2		AB12		
2	IO_L90N_2		AA3		
2	IO_L90P_2		AA4		
3	IO_L90N_3		AB3		
3	IO_L90P_3		AB4		
3	IO_L89N_3		AB6		
3	IO_L89P_3		AB7		
3	IO_L88N_3		AB9		
3	IO_L88P_3		AB10		
3	IO_L87N_3/VREF_3		AC3		
3	IO_L87P_3		AC4		
3	IO_L86N_3		AC11		
3	IO_L86P_3		AC12		
3	IO_L85N_3		AC6		
3	IO_L85P_3		AC7		
3	IO_L60N_3		AC9		
3	IO_L60P_3		AC10		
3	IO_L59N_3		AD9		
3	IO_L59P_3		AD10		
3	IO_L58N_3		AD1		
3	IO_L58P_3		AD2		
3	IO_L57N_3/VREF_3		AD3		
3	IO_L57P_3		AD4		
3	IO_L56N_3		AD11		
3	IO_L56P_3		AD12		
3	IO_L55N_3		AD5		
3	IO_L55P_3		AD6		
3	IO_L54N_3		AD7		
3	IO_L54P_3		AD8		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
4	IO_L87P_4/VREF_4		AP15	NC	
4	IO_L37N_4		AV15		
4	IO_L37P_4		AU15		
4	IO_L38N_4		AY14		
4	IO_L38P_4		AY15		
4	IO_L39N_4		AM16		
4	IO_L39P_4		AL16		
4	IO_L43N_4		AP16		
4	IO_L43P_4		AN16		
4	IO_L44N_4		AR16		
4	IO_L44P_4		AT16		
4	IO_L45N_4		AV16		
4	IO_L45P_4/VREF_4		AU16		
4	IO_L46N_4		AL18		
4	IO_L46P_4		AL17		
4	IO_L47N_4		AM17		
4	IO_L47P_4		AN17		
4	IO_L48N_4		AR17		
4	IO_L48P_4		AP17		
4	IO_L49N_4		AU17		
4	IO_L49P_4		AT17		
4	IO_L50_4/No_Pair		AW16		
4	IO_L53_4/No_Pair		AW17		
4	IO_L54N_4		AN18		
4	IO_L54P_4		AM18		
4	IO_L55N_4		AT18		
4	IO_L55P_4		AR18		
4	IO_L56N_4		AV17		
4	IO_L56P_4		AV18		
4	IO_L57N_4		AY18		
4	IO_L57P_4/VREF_4		AY17		
4	IO_L58N_4		AM19		
4	IO_L58P_4		AL19		
4	IO_L59N_4		AP19		
4	IO_L59P_4		AN19		
4	IO_L60N_4		AT19		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
6	IO_L52N_6		AE42		
6	IO_L53P_6		AE32		
6	IO_L53N_6		AE33		
6	IO_L54P_6		AD35		
6	IO_L54N_6		AD36		
6	IO_L55P_6		AD37		
6	IO_L55N_6		AD38		
6	IO_L56P_6		AD31		
6	IO_L56N_6		AD32		
6	IO_L57P_6		AD39		
6	IO_L57N_6/VREF_6		AD40		
6	IO_L58P_6		AD41		
6	IO_L58N_6		AD42		
6	IO_L59P_6		AD33		
6	IO_L59N_6		AD34		
6	IO_L60P_6		AC33		
6	IO_L60N_6		AC34		
6	IO_L85P_6		AC36		
6	IO_L85N_6		AC37		
6	IO_L86P_6		AC31		
6	IO_L86N_6		AC32		
6	IO_L87P_6		AC39		
6	IO_L87N_6/VREF_6		AC40		
6	IO_L88P_6		AB33		
6	IO_L88N_6		AB34		
6	IO_L89P_6		AB36		
6	IO_L89N_6		AB37		
6	IO_L90P_6		AB39		
6	IO_L90N_6		AB40		
7	IO_L90P_7		AA39		
7	IO_L90N_7		AA40		
7	IO_L89P_7		AB31		
7	IO_L89N_7		AA31		
7	IO_L88P_7		AA36		
7	IO_L88N_7/VREF_7		AA37		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	IO_L40P_2	R5	
2	IO_L41N_2	V6	
2	IO_L41P_2	V7	
2	IO_L42N_2	R3	
2	IO_L42P_2	P3	
2	IO_L43N_2	R1	
2	IO_L43P_2	R2	
2	IO_L44N_2	W10	
2	IO_L44P_2	W11	
2	IO_L45N_2	T7	
2	IO_L45P_2	R7	
2	IO_L46N_2/VREF_2	T4	
2	IO_L46P_2	T5	
2	IO_L47N_2	W9	
2	IO_L47P_2	Y10	
2	IO_L48N_2	T1	
2	IO_L48P_2	T2	
2	IO_L49N_2	U6	
2	IO_L49P_2	T6	
2	IO_L50N_2	W7	
2	IO_L50P_2	Y8	
2	IO_L51N_2	U4	
2	IO_L51P_2	T3	
2	IO_L52N_2/VREF_2	U2	
2	IO_L52P_2	U3	
2	IO_L53N_2	Y11	
2	IO_L53P_2	Y12	
2	IO_L54N_2	V4	
2	IO_L54P_2	V5	
2	IO_L55N_2	V1	
2	IO_L55P_2	V2	
2	IO_L56N_2	Y6	
2	IO_L56P_2	Y7	
2	IO_L57N_2	W5	
2	IO_L57P_2	W6	
2	IO_L58N_2/VREF_2	W3	
2	IO_L58P_2	V3	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L26P_7	V31	
7	IO_L26N_7	U31	
7	IO_L25P_7	L41	
7	IO_L25N_7	L42	
7	IO_L24P_7	K40	
7	IO_L24N_7	L40	
7	IO_L23P_7	T34	
7	IO_L23N_7	T35	
7	IO_L22P_7	L38	
7	IO_L22N_7/VREF_7	L39	
7	IO_L21P_7	K36	
7	IO_L21N_7	L36	
7	IO_L20P_7	T32	
7	IO_L20N_7	T33	
7	IO_L19P_7	K41	
7	IO_L19N_7	K42	
7	IO_L18P_7	K37	
7	IO_L18N_7	K38	
7	IO_L17P_7	R34	
7	IO_L17N_7	R35	
7	IO_L16P_7	H42	
7	IO_L16N_7/VREF_7	J41	
7	IO_L15P_7	J39	
7	IO_L15N_7	J40	
7	IO_L14P_7	R32	
7	IO_L14N_7	R33	
7	IO_L13P_7	J36	
7	IO_L13N_7	J37	
7	IO_L12P_7	H40	
7	IO_L12N_7	H41	
7	IO_L11P_7	T31	
7	IO_L11N_7	R31	
7	IO_L10P_7	H38	
7	IO_L10N_7/VREF_7	H39	
7	IO_L09P_7	H36	
7	IO_L09N_7	H37	
7	IO_L08P_7	P34	